

What is claimed is:

1. An optical module mounted body comprising:
a mounting board having a mounting surface with a plurality of holes
5 formed thereon;
an optical module placed on the mounting surface; and
a securing member configured to secure said optical module, said
securing member including an upper portion, a plurality of legs extending
from the upper portion and a plurality of engagement portions formed at ends
10 of the plurality of legs,
wherein said optical module is held between said mounting board and
said securing member such that the upper portion of said securing member
abuts on an upper surface of said optical module, and
wherein the plurality of legs are inserted in the plurality of holes, the
15 plurality of engagement portion engaging with said mounting board.
2. The optical module mounted body according to claim 1, wherein the
plurality of engagement portion engages with said mounting board on an
undersurface opposite said mounting surface.
20
3. The optical module mounted body according to claim 1, wherein said
optical module is pressed against the mounting surface by the upper portion
of said securing member.
- 25 4. The optical module mounted body according to claim 1, wherein the
upper portion of said securing member is convex towards the upper surface
of said optical module.
5. The optical module mounted body according to claim 1,
30 wherein said optical module comprises at least one lead pins for
electrical connection to external circuits; and
wherein the at least one lead pins are soldered to said mounting board.
6. The optical module mounted body according to claim 5,

wherein said mounting board is formed with wiring holes, and
wherein the at least one lead pins are inserted in the wiring holes and
soldered to said mounting board.

5 7. The optical module mounted body according to claim 1, further
comprising a heat conducting member interposed between a bottom surface
of said optical module and the mounting surface of said mounting board.

10 8. The optical module mounted body according to claim 1,
wherein said mounting board comprises at least one heat conducting
member connecting continuously the mounting surface and an undersurface
opposite the mounting surface, each end of said at least one heat conducting
member being coplanar with each one of the mounting surface and the
undersurface.

15 9. The optical module mounted body according to claim 1, wherein said
securing member has two legs to oppose each other on both lateral sides of
said optical module.

20 10. The optical module mounted body according to claim 1, wherein said
securing member has two legs and one leg, the two legs and the one leg
opposing on both longitudinal sides of said optical module.

25 11. The optical module mounted body according to claim 1, wherein said
securing
member has two legs on each lateral side of said optical module.

30 12. The optical module mounted body according to claim 11,
wherein said optical module comprises a plurality of lead pins for
electrical connection to external circuits, the plurality of lead pins protruding
on both lateral sides of said optical module; and
wherein a part of the plurality of lead pins protruding on each lateral
side of said optical module are received between the two legs on the same
side.

13. A securing method of an optical module comprising:
placing said optical module on a mounting surface of a mounting
board;
5 placing a securing member over said optical module,
said securing member including an upper portion to abut
on an upper surface of said optical module,
a plurality of legs extending from the upper portion
generally alongside of said optical module, and
10 a plurality of engagement portions being formed at ends of
the plurality of legs; and
attaching said securing member to said mounting board, the plurality of
legs being inserted in a plurality of holes formed on said mounting board and
the plurality of engagement portions being engaged with said mounting
15 board.
14. The method according to claim 13, wherein the upper portion of said
securing member is adapted to press the upper surface of said optical module
against the mounting surface.
- 20 15. The method according to claim 13, wherein said upper portion of said
securing member is convex towards said upper surface of said optical
module.
- 25 16. The method according to claim 13, further comprising:
inserting a lead pin of said optical module in a wiring hole formed on
said mounting board; and
soldering the lead pin to said mounting board.
- 30 17. An optical module mounted body comprising:
means for mounting said optical module ; and
means for engaging a securing member with said mounting board, said
optical module being secured therewith on said mounting board. .

18. The optical module mounted body according to claim 17, further comprising means for pressing said optical module against the mounting surface.

5 19. A mounting board comprising:

a plate member having a mounting surface and an undersurface opposite the mounting surface; and

at least one heat conducting member embedded in said plate member and connecting continuously said mounting surface and said undersurface of
10 said plate member;

wherein each of said at least one heat conducting member are exposed on each one of said mounting surface and said undersurface.

20. The mounting board according to claim 19, wherein said at least one
15 heat conducting member is coplanar with said mounting surface.